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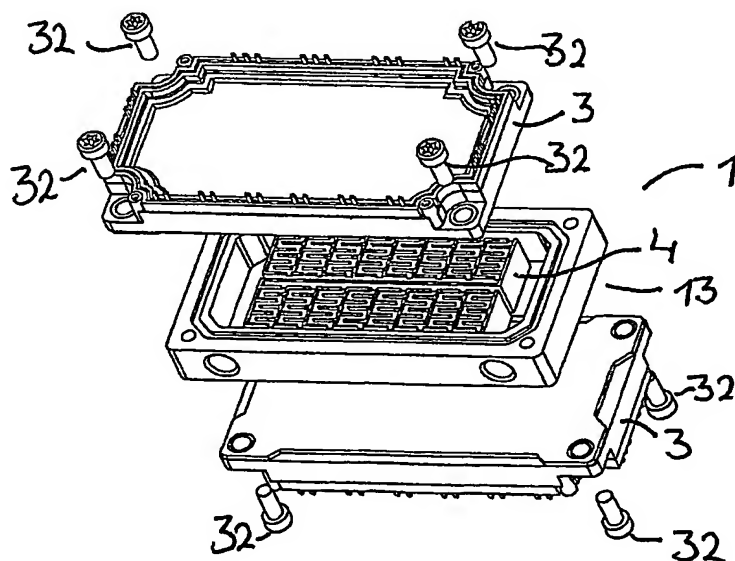
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(54) Title: FLOW DISTRIBUTING UNIT AND COOLING UNIT



(57) Abstract: A distributor (1) for distributing a flow of cooling fluid over surface(s) (3) to be cooled has a housing (13) manufactured in a single piece with inlet (8) and outlet (9) manifolds and a plurality of flow cells (26, 27, 28, 29) which makes it easier and more cost effective to manufacture the distributor (1). The flow cells (26, 27, 28, 29) may be connected in parallel between the manifolds (8, 9) and may be adapted to cool two or more surfaces (3) simultaneously. Also disclosed is a fluid-coolable unit comprising the distributor (1) is furthermore suitable for removing heat from an electronic circuit, such as integrated circuit or CPU.